

Chiplet Market by Processor (Field-Programmable Gate Array (FPGA), Central Processing Unit (CPU), Graphics Processing Unit (GPU), SOC, AI ASIC Co-Processor), Packaging Technology (SiP, FCCSP, FCBGA, 2.5D/3D, WLCSP, Fan-Out) - Global Forecast to 2030

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Report description:

The chiplet market is projected to reach USD 157.23 billion by 2030 from USD 51.94 billion in 2025, at a CAGR of 24.8% during the forecast period.

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The chiplet market is driven by the increasing demand for high-performance, power-efficient, and cost-effective semiconductor solutions in AI, data center, and HPC applications. Its modular design enables faster development cycles and better scalability compared to traditional monolithic chips. However, the market faces challenges such as complex design integration, interoperability issues, and high initial development costs. Additionally, the absence of standardized interfaces among chiplets from different vendors limits broader ecosystem adoption.

"AI ASIC coprocessor segment of chiplet market to witness high growth during forecast period."

The AI ASIC processor segment is expected to record the highest growth rate during the forecast period due to increasing demand for specialized hardware optimized for AI and machine learning workloads. These processors provide superior performance, lower latency, and greater energy efficiency compared to general-purpose CPUs or GPUs. The growing use of AI in data centers, autonomous systems, and edge devices is further speeding up their adoption. Additionally, advancements in chiplet-based AI ASIC designs are allowing for better scalability and quicker delivery of AI-driven applications.

"Enterprise electronics segment will hold the largest share in the chiplet market during the forecast period."

The enterprise sector is expected to significantly drive the chiplet market as organizations increasingly adopt high-performance computing and AI-driven solutions for data analytics, cloud services, and automation. Enterprises need scalable, energy-efficient processors to manage complex workloads, making chiplet-based architectures an ideal choice. The modularity of chiplets allows for customized computing solutions tailored to specific enterprise needs, boosting performance and cost efficiency. Growing investments in data centers, digital transformation, and edge computing further increase demand. Additionally, leading tech companies are utilizing chiplet designs to accelerate innovation and optimize infrastructure performance, fueling market growth. "China is expected to witness the fastest growth in the chiplet market during the forecast period."

Asia Pacific is expected to dominate the chiplet market during the forecast period. China is predicted to hold the largest share within the Asia Pacific chiplet market due to its rapidly growing semiconductor manufacturing and packaging ecosystem. The country is heavily investing in domestic chip production through government initiatives like the "Made in China 2025" plan to reduce reliance on foreign technologies. Major Chinese companies are increasingly adopting chiplet architectures to improve computing performance and design flexibility for AI, 5G, and consumer electronics applications. A strong electronics supply chain and high consumer demand further support market growth. Additionally, partnerships between Chinese foundries and global semiconductor firms are speeding up technology adoption and expanding production capacity.

Extensive primary interviews were conducted with key industry experts in the chiplet market to determine and verify the market size for various segments and subsegments gathered through secondary research. The breakdown of primary participants for the report is shown below:

By Company Type: Tier 1 - 50%, Tier 2 - 30%, and Tier 3 - 20%

By Designation: C Level - 20%, Director Level - 50%, Others-30%

By Region: North America - 30%, Europe - 20%, Asia Pacific - 40%, ROW- 10%

The report highlights key players in the chiplet market along with their market rankings. Prominent companies profiled include Intel Corporation (US), Advanced Micro Devices, Inc. (US), Apple Inc. (US), IBM (US), Marvell (US), MediaTek Inc. (Taiwan), NVIDIA Corporation (US), Achronix Semiconductor Corporation (US), Ranovus (Canada), and ASE Technology Holding Co., Ltd. (Taiwan). Besides these, Netronome (US), Cadence Design Systems, Inc. (US), and Synopsys, Inc. (US), SiFive, Inc. (US), ALPHAWAVE SEMI (UK), Eliyan (US), Ayar Labs, Inc. (US), Tachyum (US), X-Celeprint (Ireland), Kandou Bus SA (Switzerland), NHanced Semiconductors (US), Tenstorrent (Canada), Chipuller (China), and Rain Neuromorphics (US) are among the emerging companies in the chiplet market.

Research Coverage:

This research report classifies the chiplet market based on processor type, packaging technology, end-use application, and region. It outlines the major drivers, restraints, challenges, and opportunities related to the chiplet market and provides forecasts through 2030. Additionally, the report includes leadership mapping and analysis of all the companies involved in the chiplet ecosystem.

Reason to Buy This Report

The report will assist market leaders and new entrants by providing approximate revenue figures for the overall chiplet market and its subsegments. It will help stakeholders understand the competitive landscape, gain insights to better position their businesses, and develop effective go-to-market strategies. Additionally, the report offers stakeholders an understanding of market trends and key factors such as drivers, restraints, challenges, and opportunities.

The report provides insights on the following pointers:

- Analysis of key drivers (adoption of high-performance computing servers in various sectors, proliferation of data centers worldwide, adoption of advanced packaging technologies), restraints (heat management issues, lack of industry-wide interoperability standards), opportunities (development of quantum chiplets, rapid expansion of 5G infrastructure, rising incorporation of high-performance and power-efficient chiplets in medical devices, adoption of chiplets in AI and edge computing

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applications, increasing investments in autonomous vehicles) and challenges (challenges related to intellectual property (IP) protection and licensing, cybersecurity and vulnerability issues associated with chiplet-based systems) influencing the growth of the chiplet market.

- Product Development/Innovation: Detailed insights on upcoming technologies, research & development activities, and new product & service launches in the chiplet market
- Market Development: Comprehensive information about lucrative markets - the report analyzes the chiplet market across varied regions
- Market Diversification: Exhaustive information about new products & services, untapped geographies, recent developments, and investments in the chiplet market
- Competitive Assessment: In-depth assessment of market share, growth strategies and service offerings of leading players such as Intel Corporation (US), Advanced Micro Devices, Inc. (US), Apple Inc. (US), IBM (US), and Marvell (US), among others in the chiplet market

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